[Claim 1] An MEMS device comprising:

a primary substrate provided with a bump including a primary electrode; and

a secondary substrate provided with a secondary electrode on a bottom surface of a recessed portion formed by an adhesive layer,

wherein the primary substrate and the secondary substrate are joined together with the adhesive layer,

the primary electrode is electrically connected to the secondary electrode with the bump inserted into the recessed portion,

part of the bump and the adhesive layer forming the recessed portion overlap each other in a direction in which the bump is inserted into the recessed portion,

and characterized in that

a gap is provided between the adhesive layer and the bump so as to keep the adhesive layer out of contact with the bump.

[Claim 2]The MEMS device according to claim 1, wherein the bump includes an elastic core portion, and a metal film provided on a surface of the core portion.

[Claim 3]The MEMS device according to claim 2, wherein

the primary substrate is provided with a plurality of the primary electrodes,

the core portion of the bump is provided independently for each of the primary electrodes, and

the adhesive layer is provided between each pair of the core portions adjacent to each other.

[Claim 4] A head comprising:

the MEMS device according to any one of claims 1 to 3;

a pressure generating chamber formed in the secondary substrate and communicating with a nozzle; and

a piezoelectric element attached to a primary substrate side of the secondary substrate, the piezoelectric element connected to the secondary electrode and configured to cause a pressure change in a liquid in the pressure generating chamber.

[Claim 5]A liquid jet device comprising the head according to claim 4.